



20V N-CHANNEL ENHANCEMENT MODE MOSFET

Product Summary

BV _{DSS}	R _{DS(ON)} Max	I _D Max T _A = +25°C
201/	$200 \text{m}\Omega$ @ $V_{GS} = 4.5 \text{V}$	1.3A
20V	280mΩ @ V _{GS} = 2.5V	1.1A

Features and Benefits

- Low On-Resistance
- Low Input Capacitance
- Fast Switching Speed
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen- and Antimony-Free. "Green" Device (Note 3)
- For automotive applications requiring specific change control (i.e. parts qualified to AEC-Q100/101/200, PPAP capable, and manufactured in IATF 16949 certified facilities), please contact us or your local Diodes representative. https://www.diodes.com/quality/product-definitions/

Description and Applications

This MOSFET has been designed to minimize on-state resistance (R_{DS(ON)}) yet maintain superior switching performance, making it ideal for high-efficiency power management applications.

- General Purpose Interfacing Switch
- **Power Management Functions**
- **DC-DC Converters**
- Analog Switch

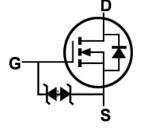
Mechanical Data

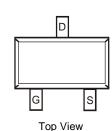
- Case: SOT323
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminal Connections Indicator: See Diagram
- Terminals: Finish—Matte Tin Annealed over Copper Lead-Frame. Solderable per MIL-STD-202, Method 208 @3
- Weight: 0.027 grams (Approximate)





SOT323





Top View

Equivalent Circuit

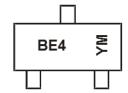
Ordering Information (Note 4)

Part Number	Case	Packaging
DMN2310UW-7	SOT323	3,000/Tape & Reel
DMN2310UW-13	SOT323	10.000/Tape & Reel

Notes:

- 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant.
- 2. See https://www.diodes.com/quality/lead-free/ for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.</p>
 4. For packaging details, go to our website at https://www.diodes.com/design/support/packaging/diodes-packaging/.

Marking Information



BE4 = Product Type Marking Code YM = Date Code Marking \overline{Y} = Year (ex: H = 2020) M = Month (ex: 9 = September)

Date Code Key

Year	2020	2021	2022	2023	2024	2025	2026	2027	2028	2029	2030	2031
Code	Н	- 1	J	K	L	М	N	0	Р	R	S	Т
Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec

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Maximum Ratings (@ $T_A = +25^{\circ}C$, unless otherwise specified.)

Characteristic	Symbol	Value	Unit		
Drain-Source Voltage	V_{DSS}	20	V		
Gate-Source Voltage	V_{GSS}	±8	V		
Continuous Drain Current (Note 6) V _{GS} = 4.5V	I _D	1.3 1.1	А		
Pulsed Drain Current (10µs Pulse, Duty Cycle = 1%	I _{DM}	4.4	Α		
Maximum Body Diode Forward Current (Note 5)		•	Is	0.6	Α

Thermal Characteristics (@ T_A = +25°C, unless otherwise specified.)

Characteristic		Symbol	Value	Unit
Total Power Dissipation (Note 5)		P_{D}	0.45	W
Thermal Resistance, Junction to Ambient (Note 5)	Steady State	$R_{ hetaJA}$	275	°C/W
Total Power Dissipation (Note 6)		P_{D}	0.55	W
Thermal Resistance, Junction to Ambient (Note 6)	Steady State	$R_{ hetaJA}$	226	°C/W
Operating and Storage Temperature Range		T _J , T _{STG}	-55 to +150	°C

Electrical Characteristics (@ T_A = +25°C, unless otherwise specified.)

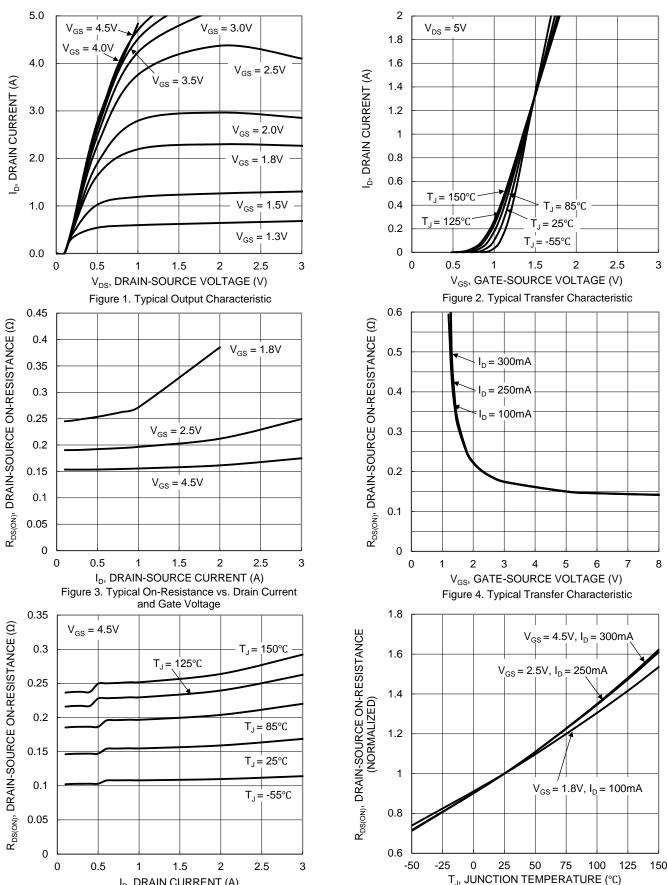
Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition
OFF CHARACTERISTICS (Note 7)						
Drain-Source Breakdown Voltage	BV _{DSS}	20	_	_	V	$V_{GS} = 0V, I_D = 250\mu A$
Zero Gate Voltage Drain Current @ T _C = +25°C	I _{DSS}		_	1.0	μΑ	$V_{DS} = 20V, V_{GS} = 0V$
Gate-Source Leakage	I _{GSS}	l	_	10	μΑ	$V_{GS} = \pm 8V$, $V_{DS} = 0V$
ON CHARACTERISTICS (Note 7)						
Gate Threshold Voltage	V _{GS(TH)}	0.45	_	0.95	V	$V_{DS} = V_{GS}$, $I_D = 250\mu A$
		I	150	200		$V_{GS} = 4.5V, I_D = 300mA$
Static Drain-Source On-Resistance	R _{DS(ON)}	I	190	280	mΩ	$V_{GS} = 2.5V, I_D = 250mA$
		l	245	380		$V_{GS} = 1.8V, I_D = 100mA$
Diode Forward Voltage	V_{SD}		0.85	1.2	V	$V_{GS} = 0V, I_{S} = 1A$
DYNAMIC CHARACTERISTICS (Note 8)			•		•	
Input Capacitance	Ciss	_	38	_	pF	
Output Capacitance	Coss	_	10	_	pF	$V_{DS} = 10V, V_{GS} = 0V,$
Reverse Transfer Capacitance	Crss	_	6	_	pF	f = 1.0MHz
Total Gate Charge	Q_g	_	0.7	_	nC	\\\ 4.5\\\\\ 40\\\
Gate-Source Charge	Q_{gs}	_	0.1	_	nC	$V_{GS} = 4.5V, V_{DS} = 10V,$
Gate-Drain Charge	Q_{gd}	_	0.1	_	nC	I _D = 1A
Turn-On Delay Time	t _{D(ON)}		4.8	_	ns	
Turn-On Rise Time	t _R	_	3	_	ns	$V_{DD} = 10V, V_{GS} = 5V,$
Turn-Off Delay Time	t _{D(OFF)}	_	181	_	ns	$R_L = 1.7\Omega$, $R_G = 6\Omega$
Turn-Off Fall Time	t _F	I	55	_	ns	

5. Device mounted on FR-4 substrate PC board, with minimum recommended pad layout.

- 6. Device mounted on FR-4 substrate PC board, 2oz copper, with thermal bias to bottom layer 1inch square copper plate.
- 7. Short duration pulse test used to minimize self-heating effect.
- 8. Guaranteed by design. Not subject to product testing.

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I_D, DRAIN CURRENT (A) Figure 5. Typical On-Resistance vs. Drain Current

and Junction Temperature



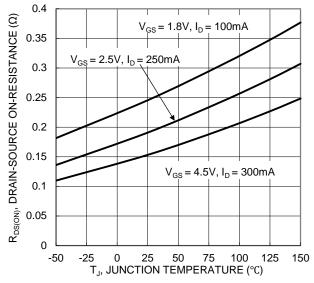


Figure 7. On-Resistance Variation with Junction Temperature

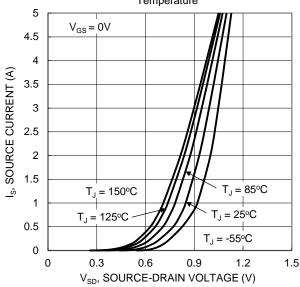


Figure 9. Diode Forward Voltage vs. Current

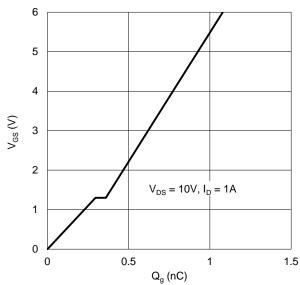


Figure 11. Gate Charge

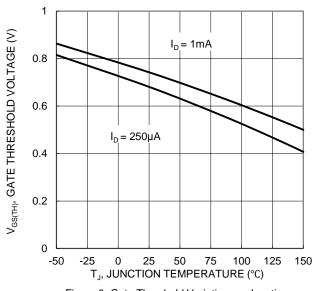


Figure 8. Gate Threshold Variation vs. Junction Temperature

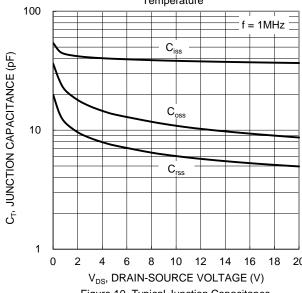


Figure 10. Typical Junction Capacitance

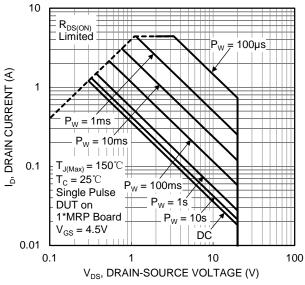


Figure 12. SOA, Safe Operation Area



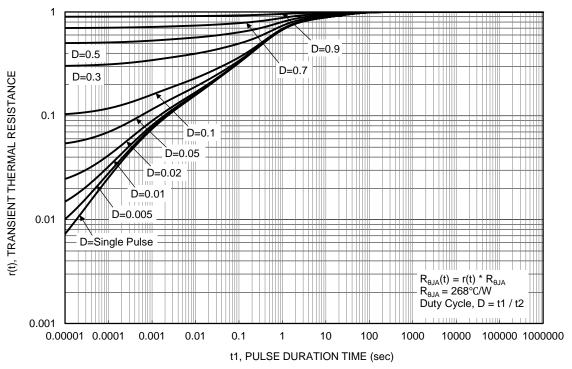
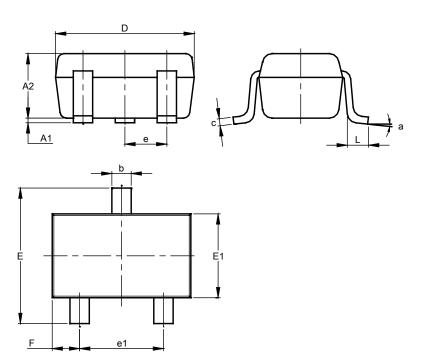


Figure 13. Transient Thermal Resistance



Package Outline Dimensions

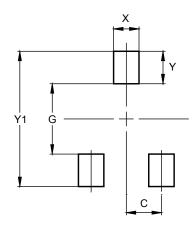
Please see http://www.diodes.com/package-outlines.html for the latest version.



SOT323						
Dim	Min	Max	Тур			
A1	0.00	0.10	0.05			
A2	0.90	1.00	0.95			
b	0.25	0.40	0.30			
С	0.10	0.18	0.11			
D	1.80	2.20	2.15			
Е	2.00	2.20	2.10			
E1	1.15	1.35	1.30			
е	0.650 BSC					
e1	1.20	1.40	1.30			
F	0.375	0.475	0.425			
L	0.25	0.40	0.30			
а	0°	8°				
All Dimensions in mm						

Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.



Dimensions	Value
Dilliensions	(in mm)
С	0.650
G	1.300
X	0.470
Y	0.600
Y1	2.500



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